Dear Product Change Notices Newark,

Here’s your personalized quality information concerning products Newark purchased from NXP. For detailed information we invite you to view this notification online.

This notice is NXP Company Proprietary.

Management Summary
NXP is changing the packing format from tray to brick for 30 LPC Microcontroller products.

Change Category
- Wafer Fab Process
- Wafer Fab Materials
- Wafer Fab Location
- Assembly [ ] Product Marking [ ] Test Location [ ] Design
- Assembly [ ] Mechanical Specification [ ] Test Process [ ] Errata
- Assembly [X] Location Packing/Shipping/Labeling [ ] Test Equipment [ ] Electrical spec./Test coverage
- Firmware
- Other

LPC Microcontroller Product Tray to Brick Packing Change

Description of Change
NXP is changing the packing format from single-tray to 5-tray (brick) for 30 LPC Microcontroller products.

This will result in the creation of new part numbers to order and new Minimum Order Quantities (MOQs). A complete list with the new orderable part numbers, including the new packing and MOQ, is attached for your reference.

There is no change to the products, only the packing method and packing quantity.

The Distributor Price Book has been updated with new part numbers.

Upon the effective date of this PCN, NXP will only accept purchase orders for limited quantities of the old (single tray) packing.

Reason for Change
This change will bring significant freight cost savings to our customers by decreasing the use of boxes and...
shipping volume by 60-80% on average.

**Identification of Affected Products**
Replacement part type created, see Parts Affected list

<table>
<thead>
<tr>
<th>Product Availability</th>
</tr>
</thead>
<tbody>
<tr>
<td>Sample Information</td>
</tr>
<tr>
<td>Not applicable</td>
</tr>
<tr>
<td>Production</td>
</tr>
<tr>
<td>Planned first shipment 06-Apr-2020</td>
</tr>
</tbody>
</table>

**Anticipated Impact on Form, Fit, Function, Reliability or Quality**
No impact on form, fit, function, reliability or quality.

**Disposition of Old Products**
Existing inventory will be shipped until depleted

**Additional Information**
Affected products and sales history information: see attached file
Self qualification: view online
Additional documents: view online

**Timing and Logistics**
In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 10-May-2020.

**Contact and Support**
For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:
**Name**
Tim Camenzind
**Position**
Quality Manager
**e-mail address**
tim.camenzind@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.
Customer Focus, Passion to Win.

NXP Quality Management Team.

**About NXP Semiconductors**

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile and computing applications.

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